Environmental and Package Testing Data for PowerPAK ChipFET					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
BOND INT	80	40,000	200°C + N2	0	0.00
HAST	330	33,000	130°C, 85%RH	0	0.00
Pressure Pot	330	31,680	121°, 15 PSIG	0	0.00
Solderability	90	720	883 M2003	0	0.00
Temp Cycle	330	330,000	−65°C−150°C	0	0.00